

1. (amended) A silicon wafer having a B-stageable underfill material deposited on one face of the wafer, the B-stageable underfill comprising a combination of two chemical compositions,
 - a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and
 - a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,
 - the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,
 - the curing temperatures or curing temperature ranges sufficiently separated to allow the first composition to cure without curing the second composition,
 - characterized in that the first composition has been cured and the second composition is uncured.
7. (amended) A B-stageable underfill composition comprising a combination of two chemical compositions,
 - a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and
 - a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,

the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,

the curing temperatures or curing temperature ranges sufficiently separated to allow the first composition to cure without curing the second composition.